

ABSTRACT

The purpose of the present invention is to provide an electroconductive adhesive composition that does not readily peel from an adherend material even when subjected to repeated temperature changes, and that furthermore has excellent thermal conductivity. The present invention relates to an electroconductive adhesive composition containing an organic acid (A) having an acid dissociation constant pKa of 4.8 or lower and an electroconductive filler (B), the electroconductive adhesive composition containing 0.01-0.2% by mass of the organic acid (A) and at least 85% by mass of the electroconductive filler (B) with respect to the entire quantity of the electroconductive adhesive composition.